

Description

The VM13218165B and VM23218165B are 1M × 32-bit and 2M × 32-bit dynamic RAM modules. It is mounted by 2/4 pieces of 1M × 16 DRAM (VG2618165BB), and each in a standard 42 pin plastic SOJ packages. The VM13218165B and VM23218165B makes high density possible without utilizing the surface mount technology on the printed circuit board. Decoupling capacitors are mounted adjacent to each DRAM for noise reduction.

Features

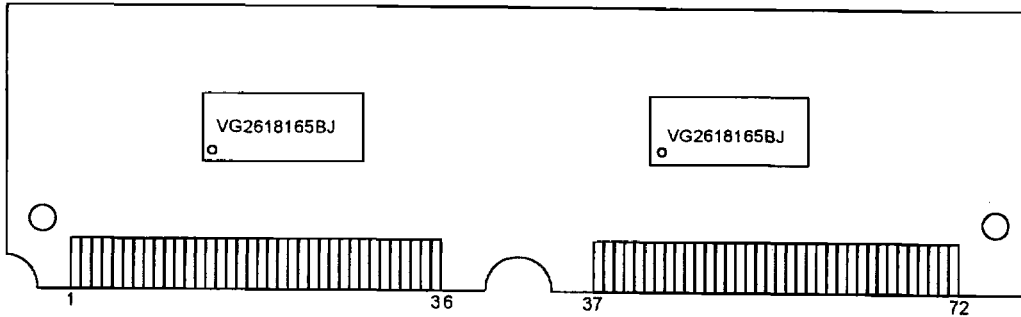
VM13218165B:

- 1,048,576 word by 32 bits organization
- Single 5V ($\pm 10\%$) power supply
- High speed t_{RAC} access time : 60/70ns(max)
- Low power dissipation
 - Active mode : 1.98/1.87 W(Max)
 - Standby mode : 11mW(Max)
- Extended-data-out (EDO) page mode capability
- TTL compatible I/O levels
- 1024 refresh cycles during a 16 ms period
- Multiple refresh modes capability
 - \overline{RAS} only refresh, \overline{CAS} before \overline{RAS} refresh and hidden refresh
- 72 pin single in-line memory module
- JEDEC Standard pinout

VM23218165B:

- 2,097,152 word by 32 bits organization
- Single 5V ($\pm 10\%$) power supply
- High speed t_{RAC} access time : 60/70ns(max)
- Low power dissipation
 - Active mode : 2.0/1.89 W(Max)
 - Standby mode : 22mW(Max)
- Extended-data-out (EDO) page mode capability
- TTL compatible I/O levels
- 1024 refresh cycles during a 16 ms period
- Multiple refresh modes capability
 - \overline{RAS} only refresh, \overline{CAS} before \overline{RAS} refresh and hidden refresh
- 72 pin single in-line memory module
- JEDEC Standard pinout

Pin assignment (Front View)



Pin Out

Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name	Pin	Name
1	V _{SS}	13	A1	25	DQ23	37	NC	49	DQ9	61	DQ14
2	DQ1	14	A2	26	DQ8	38	NC	50	DQ25	62	DQ31
3	DQ17	15	A3	27	DQ24	39	V _{SS}	51	DQ10	63	DQ15
4	DQ2	16	A4	28	A7	40	CAS ₀	52	DQ26	64	DQ32
5	DQ18	17	A5	29	NC	41	CAS ₂	53	DQ11	65	DQ16
6	DQ3	18	A6	30	V _{CC}	42	CAS ₃	54	DQ27	66	NC
7	DQ19	19	NC	31	A8	43	CAS ₁	55	DQ12	67	PD1
8	DQ4	20	DQ5	32	A9	44	RAS ₀	56	DQ28	68	PD2
9	DQ20	21	DQ21	33	NC/*RAS ₃	45	NC/*RAS ₁	57	DQ13	69	PD3
10	V _{CC}	22	DQ6	34	RAS ₂	46	NC	58	DQ29	70	PD4
11	NC	23	DQ22	35	NC	47	WE	59	V _{CC}	71	NC
12	A0	24	DQ7	36	NC	48	NC	60	DQ30	72	V _{SS}

* : 2M x 32 Version

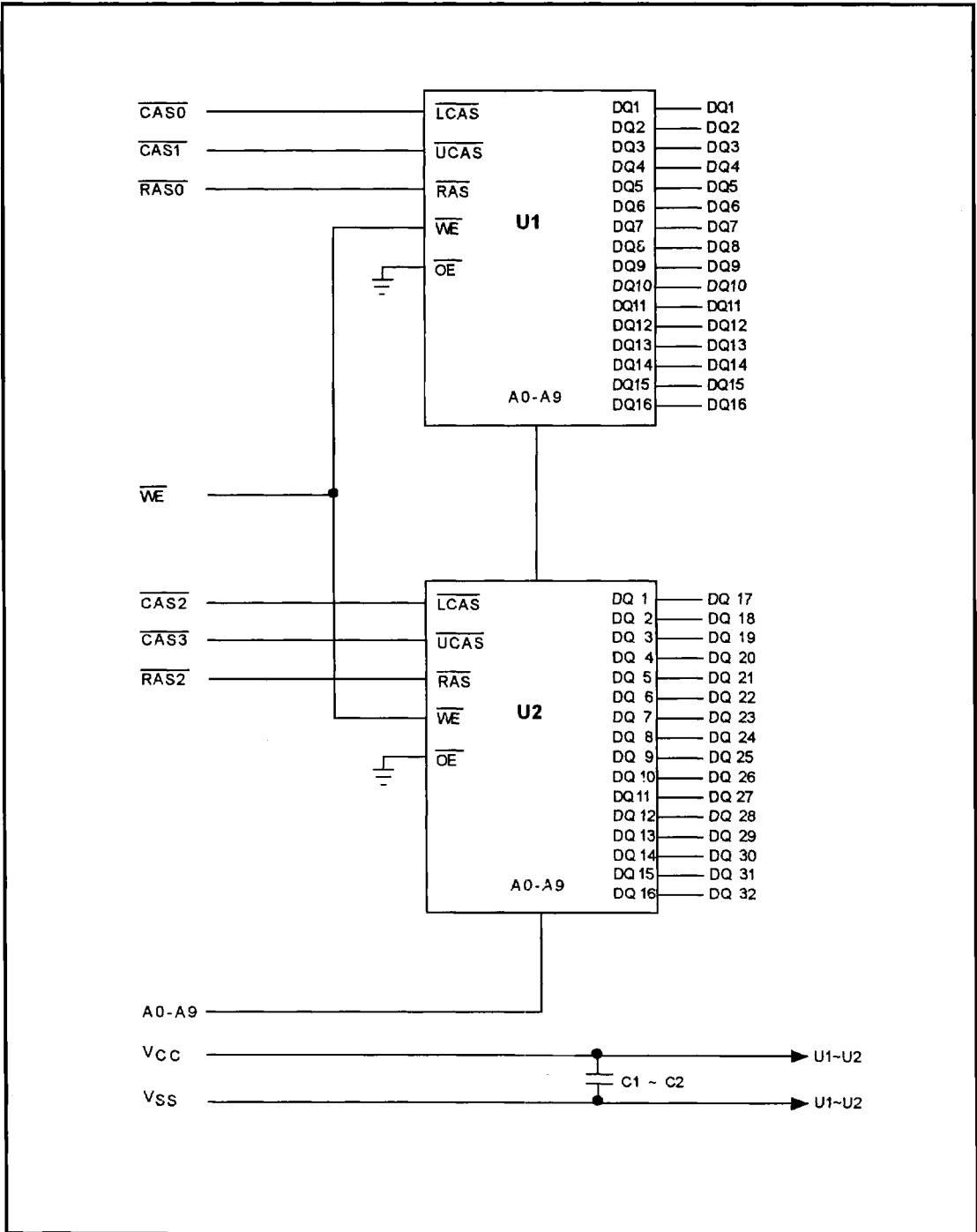
Presence-detect (1M x 32)

Name	Pin No	60ns	70ns
PD1	67	V _{SS}	V _{SS}
PD2	68	V _{SS}	V _{SS}
PD3	69	NC	V _{SS}
PD4	70	NC	NC

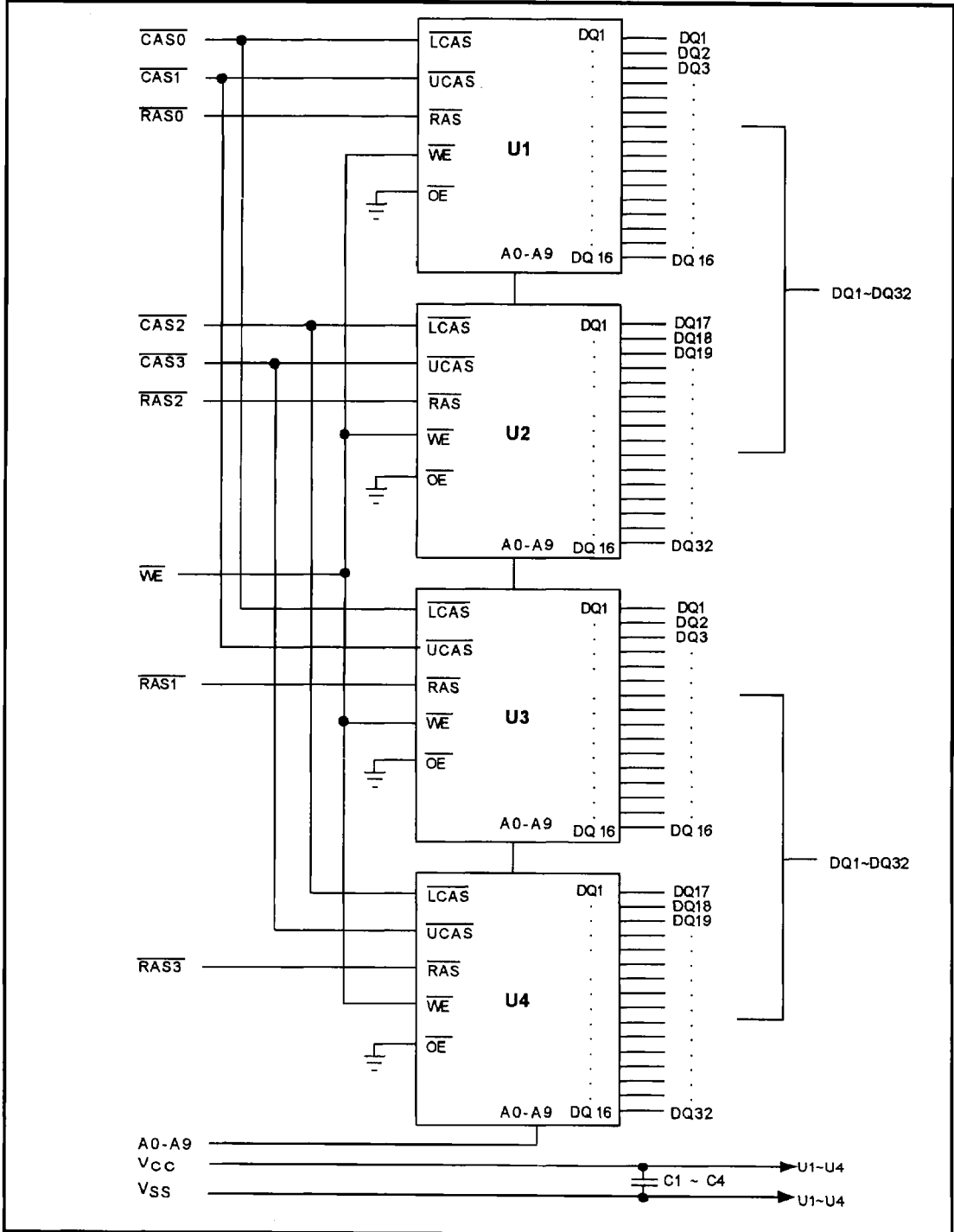
Presence-detect (2M x 32)

Name	Pin No	60ns	70ns
PD1	67	NC	NC
PD2	68	NC	NC
PD3	69	NC	V _{SS}
PD4	70	NC	NC

Block Diagram (VM13218165)B



Block Diagram (VM23218165B)



Truth Table

FUNCTION		$\overline{\text{RAS}}$	$\overline{\text{CAS}}$	$\overline{\text{WE}}$	ADDRESSES		DQ _s
					ROW	COL	
STANDBY		H	H→X	X	X	X	High-Z
READ		L	L	H	ROW	COL	Data-Out
WRITE (EARLY WRITE)		L	L	L	ROW	COL	Data-In
EDO PAGE MODE READ	1st Cycle	L	H→L	H	ROW	COL	Data-Out
	2nd Cycle	L	H→L	H	n/a	COL	Data-Out
EDO PAGE MODE WRITE	1st Cycle	L	H→L	L	ROW	COL	Data-In
	2nd Cycle	L	H→L	L	n/a	COL	Data-In
HIDDEN REFRESH	READ	L→H→L	L	H	ROW	COL	Data-Out
	WRITE	L→H→L	L	L	ROW	COL	Data-In
RAS ONLY REFRESH		L	H	X	ROW	n/a	High-Z
CBR REFRESH		H→L	L	X	X	X	High-Z

Absolute Maximum Ratings

Parameter	NAME	Value	Unit	
Voltage on any pin relative to Vss	V_T	-1.0 to +7.0	V	
Supply voltage relative to Vss	V_{CC}	-1.0 to +7.0	V	
Short circuit output current	I_{OUT}	50	mA	
Power dissipation	P_D	1M x 32	2	W
		2M x 32	4	
Operating temperature	T_{OPT}	0 to +70	°C	
Storage temperature	T_{STG}	-55 to +125	°C	

Recommended DC Operating Conditions

Parameter/Condition	NAME	Min	Typ	Max	Unit
Supply Voltage	V_{CC}	4.5	5.0	5.5	V
Input High Voltage, all inputs	V_{IH}	2.4	—	$V_{CC}+1.0$	V
Input Low Voltage, all inputs	V_{IL}	-1.0	—	0.8	V

Capacitance
 $T_a=25^\circ\text{C}, V_{CC}=5V \pm 10\%, f=1\text{MHZ}$

Parameter	Symbol	Size	Typ	Max	Unit	Note
Input capacitance(Address)	C_{I1}	1M x 32	-	32	pF	1
		2M x 32	-	42		
Input capacitance ($\overline{\text{RAS0}}, \overline{\text{RAS2}}$) ($\overline{\text{RAS0}} \sim \overline{\text{RAS3}}$)	C_{I2}	1M x 32	-	21	pF	1
		2M x 32	-	23		
Input capacitance ($\overline{\text{CAS0}} \sim \overline{\text{CAS3}}$)	C_{I3}	1M x 32	-	20	pF	
		2M x 32	-	27		
Input Capacitance ($\overline{\text{WE}}$)	C_{I4}	1M x 32	-	32	pF	
		2M x 32	-	46		
Output capacitance (Data-in, Data-out)	$C_{I/O}$	1M x 32	-	17	pF	1, 2
		2M x 32	-	24		

Note : 1. Capacitance measured with effective capacitance measuring method.

 2. $\overline{\text{RAS}}, \overline{\text{CAS}} = V_{IH}$ to disable Dout.

DC Characteristics ;
 (Ta=0 to 70°C, V_{CC}=+5V±10%, V_{SS}=0V)

Parameter	Symbol	Test Conditions	size	-6		-7		Unit	Notes
				Min	Max	Min	Max		
Operating current	I _{CC1}	RAS cycling	1M×32	-	360	-	340	mA	1,2
		CAS cycling t _{RC} =min.	2M×32	-	364	-	344		
Standby Current	I _{CC2}	TTL interface	1M×32	-	4	-	4	mA	
		RAS, CAS = V _{IH} Dout=High-Z	2M×32	-	8	-	8		
		CMOS interface	1M×32	-	2	-	2	mA	
		RAS, CAS ≥ V _{CC} -0.2V Dout=High-Z	2M×32	-	4	-	4		
RAS-only refresh current	I _{CC3}	RAS cycling, CAS = V _{IH} t _{RC} =min.	1M×32 2M×32	- -	360 364	- -	340 344	mA	1,2
EDO page mode current	I _{CC4}	t _{PC} =min.	1M×32 2M×32	- -	220 224	- -	200 204		
CAS-before-RAS refresh current	I _{CC5}	t _{RC} =min. RAS, CAS cycling	1M×32 2M×32	- -	360 364	- -	340 344	mA	1,2
Input leakage current	I _{LI}	0V ≤ Vin ≤ 7V	1M×32 2M×32	-10 -20	10 20	-10 -20	10 20		
Output leakage current	I _{LO}	0V ≤ Vout ≤ 7V Dout=Disable	1M×32 2M×32	-10 -20	10 20	-10 -20	10 20		
Output high voltage	V _{OH}	I _{OH} =-5mA	1M×32 2M×32	2.4 2.4	- -	2.4 2.4	- -	V	
Output low voltage	V _{OL}	I _{OL} =+4.2mA	1M×32 2M×32	- -	0.4 0.4	- -	0.4 0.4		

Notes :

- I_{CC} is specified as an average current. It depends on output loading condition and cycle rate when the device is selected. I_{CC} max is specified at the output open condition.
- Address can be changed once or less while RAS = V_{IL}.
- For I_{CC4}, address can be changed once or less within one EDO page mode cycle time.

AC Characteristics

($T_a = 0$ to $+70^\circ\text{C}$, $V_{CC} = 5\text{V} \pm 10\%$, $V_{SS} = 0\text{V}$) Notes *1, *2, *3

Test conditions

- Input rise and fall times: 2ns
- Input timing reference levels :
 $V_{IH} = 2.4\text{V}$, $V_{IL} = 0.8\text{V}$

Read, Write and Refresh Cycles (Common Parameters)

Parameter	Symbol	-6		-7		Unit	Notes
		Min	Max	Min	Max		
Random read or write cycle time	t_{RC}	110	-	124	-	ns	
RAS precharge time	t_{RP}	40	-	50	-	ns	
CAS precharge time in normal mode	t_{CPN}	10	-	10	-	ns	
RAS pulse width	t_{RAS}	60	10000	70	10000	ns	
CAS pulse width	t_{CAS}	10	10000	12	10000	ns	
Row address setup time	t_{ASR}	0	-	0	-	ns	
Row address hold time	t_{RAH}	10	-	10	-	ns	
Column address setup time	t_{ASC}	0	-	0	-	ns	4
Column address hold time	t_{CAH}	10	-	15	-	ns	
RAS to CAS delay time	t_{RCD}	20	42	20	50	ns	5
RAS to column address delay time	t_{RAD}	15	30	15	35	ns	6
Column address to RAS lead time	t_{RAL}	30	-	35	-	ns	
RAS hold time	t_{RSH}	15	-	18	-	ns	
CAS hold time	t_{CSH}	50	-	60	-	ns	
CAS to RAS precharge time	t_{CRP}	5	-	5	-	ns	7
Transition time (rise and fall)	t_T	1	50	1	50	ns	8
Refresh period	t_{REF}	-	16	-	16	ms	
CAS to output in Low-Z	t_{CLZ}	0	-	0	-	ns	
OE to Din delay time	t_{OED}	15	-	18	-	ns	

Read Cycle

Parameter	Symbol	-6		-7		Unit	Notes
		Min	Max	Min	Max		
Access time from RAS	t_{RAC}	-	60	-	70	ns	9
Access time from CAS	t_{CAC}	-	18	-	20	ns	10, 11
Access time from column address	t_{AA}	-	30	-	35	ns	11, 12
Read command setup time	t_{RCS}	0	-	0	-	ns	4
Read command hold time to CAS	t_{RCH}	0	-	0	-	ns	7, 13
Read command hold time to RAS	t_{RRH}	10	-	10	-	ns	13
Output buffer turn-off time	t_{OFF}	0	15	0	18	ns	14
Access time from OE	t_{OEA}	-	15	-	18	ns	
Output buffer turn-off time from OE	t_{OEZ}	0	15	0	18	ns	14

Write Cycle

Parameter	Symbol	-6		-7		Unit	Notes
		Min	Max	Min	Max		
Write command setup time	t_{WCS}	0	-	0	-	ns	4
Write command hold time	t_{WCH}	10	-	10	-	ns	
Write command pulse width	t_{WP}	10	-	10	-	ns	
Write command to \overline{RAS} lead time	t_{RWL}	15	-	18	-	ns	
Write command to \overline{CAS} lead time	t_{CWL}	15	-	18	-	ns	
Data-in setup time	t_{DS}	0	-	0	-	ns	
Data-in hold time	t_{DH}	10	-	15	-	ns	
\overline{WE} to Data-in delay	t_{WED}	10	-	10	-	ns	

Refresh Cycle

Parameter	Symbol	-6		-7		Unit	Notes
		Min	Max	Min	Max		
\overline{CAS} setup time(CBR refresh)	t_{CSR}	10	-	10	-	ns	
\overline{CAS} hold time (CBR refresh)	t_{CHR}	10	-	10	-	ns	7
\overline{RAS} precharge to \overline{CAS} hold time	t_{RPC}	5	-	5	-	ns	4

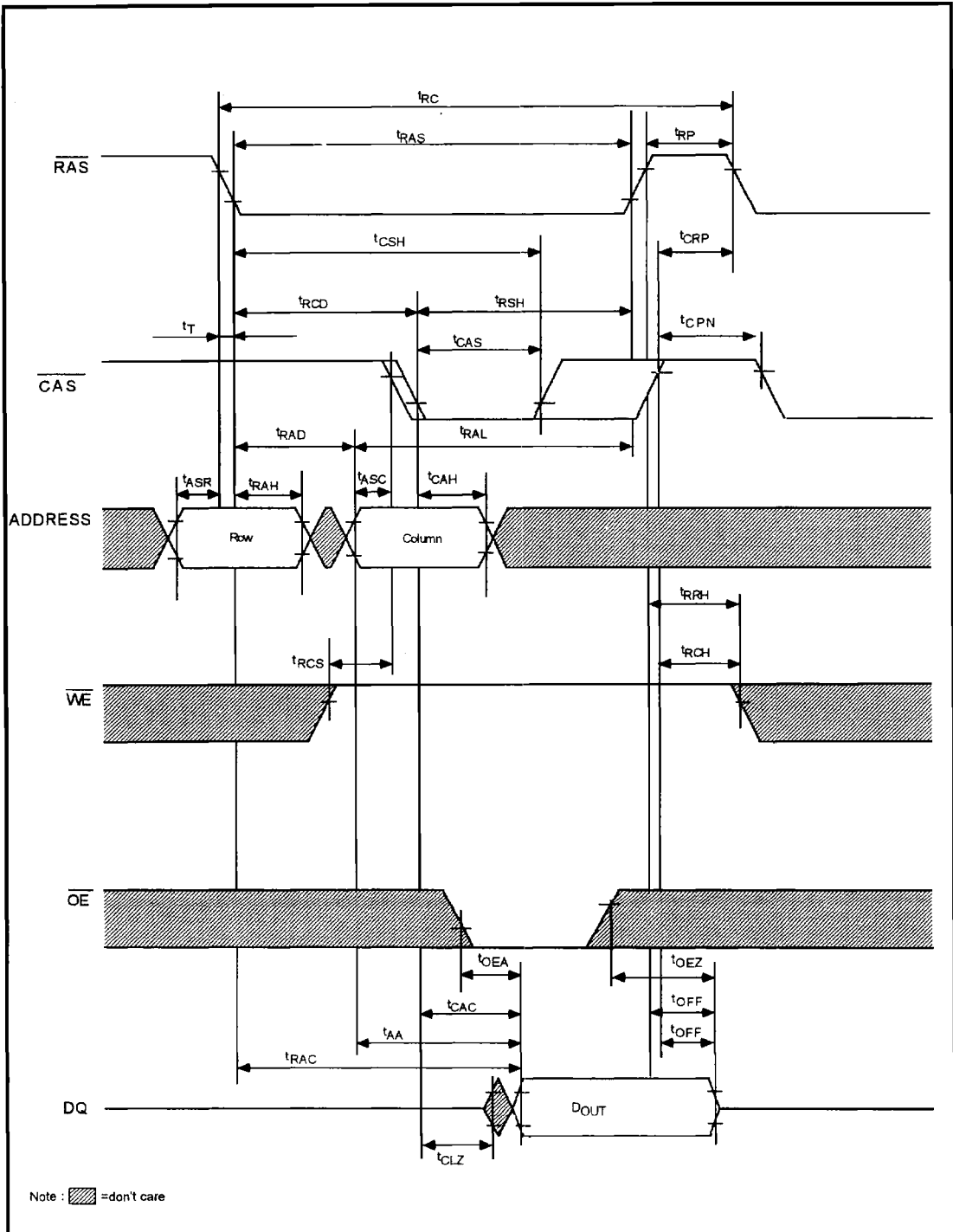
EDO Page Mode Cycle

Parameter	Symbol	-6		-7		Unit	Notes
		Min	Max	Min	Max		
EDO page mode cycle time	t_{PC}	25	-	30	-	ns	
EDO page mode \overline{CAS} precharge time	t_{CP}	10	-	10	-	ns	
EDO page mode \overline{RAS} pulse width	t_{RASP}	60	10^5	70	10^5	ns	15
Access time from \overline{CAS} precharge	t_{CPA}	-	35	-	40	ns	7,11
\overline{RAS} hold time from \overline{CAS} precharge	t_{CPRH}	35	-	40	-	ns	
OE high hold time from \overline{CAS} high	t_{OEHC}	5	-	5	-	ns	
OE high pulse width	t_{OEP}	10	-	10	-	ns	
Data Output hold after \overline{CAS} low	t_{COH}	5	-	5	-	ns	
Out disable delay from \overline{WE}	t_{WHZ}	3	10	3	10	ns	
\overline{WE} pulse width for output disable when \overline{CAS} high	t_{WPZ}	7	-	7	-	ns	

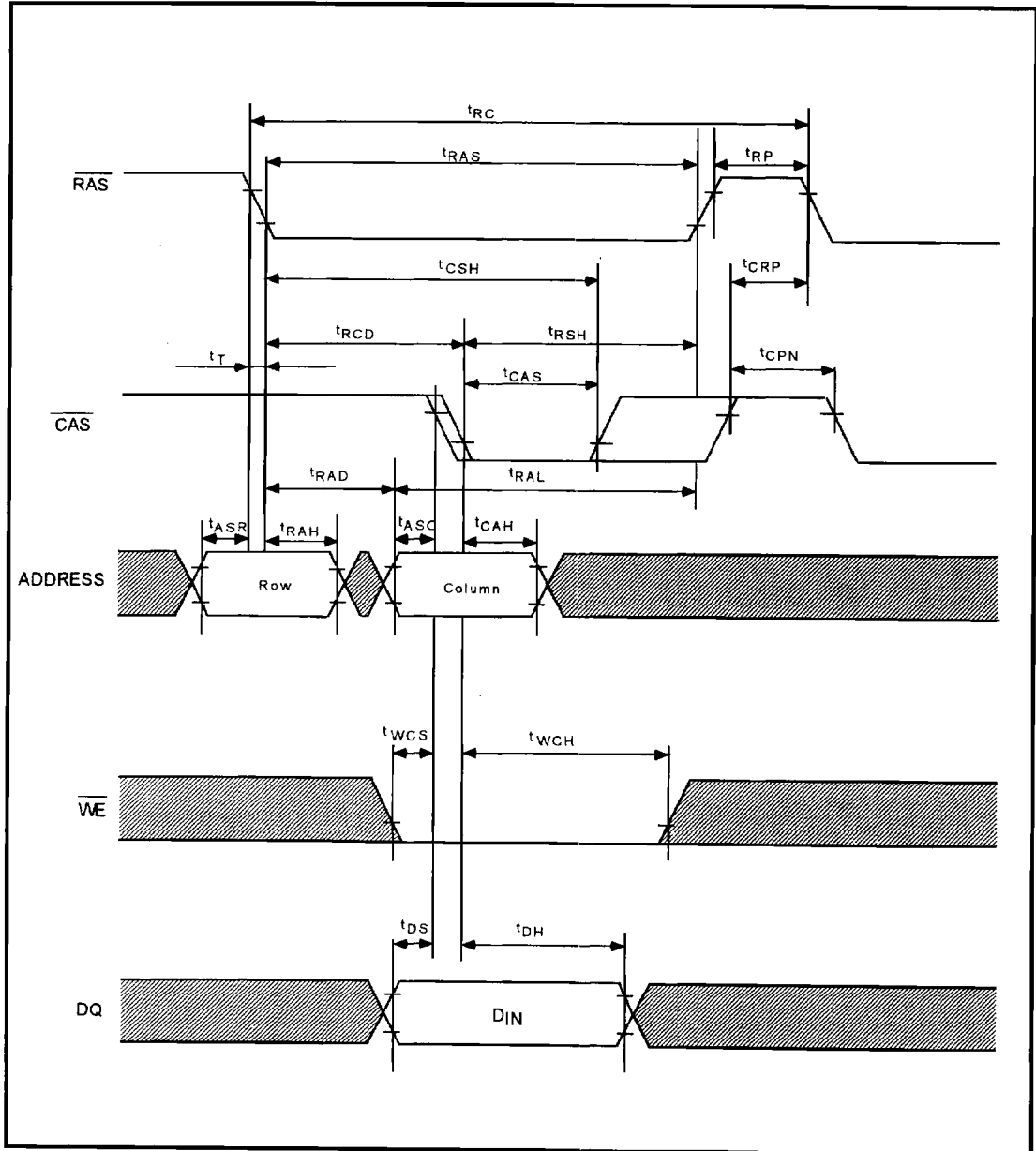
Notes :

1. AC measurements assume $t_T = 2\text{ns}$.
2. An initial pause of $100\ \mu\text{s}$ is required after power up followed by a minimum of eight initialization cycles ($\overline{\text{RAS}}$ -only refresh cycle or $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycle). If the internal refresh counter is used, a minimum of eight $\overline{\text{CAS}}$ -before- $\overline{\text{RAS}}$ refresh cycles are required.
3. All the V_{CC} and V_{SS} pins shall be supplied with the same voltages.
4. $t_{ASC}(\text{min})$, $t_{RCS}(\text{min})$, $t_{WCS}(\text{min})$ and t_{RPC} are determined by the falling edge of $\overline{\text{CAS}}$.
5. Operation with the $t_{RCD}(\text{max})$ limit insures that $t_{RAC}(\text{max})$ can be met, $t_{RCD}(\text{max})$ is specified as a reference point only, if t_{RCD} is greater than the specified $t_{RCD}(\text{max})$ limit, then access time is controlled exclusively by t_{CAC} .
6. Operation with the $t_{RAD}(\text{max})$ limit insures that $t_{RAC}(\text{max})$ can be met, $t_{RAD}(\text{max})$ is specified as a reference point only, if t_{RAD} is greater than the specified $t_{RAD}(\text{max})$ limit, then access time is controlled exclusively by t_{AA} .
7. t_{CRP} , t_{CHR} , t_{RCH} and t_{CPA} are determined by the rising edge of $\overline{\text{CAS}}$.
8. $V_{IH}(\text{min})$ and $V_{IL}(\text{max})$ are reference levels for measuring timing or input signals. Also, transition times are measured between V_{IH} and V_{IL} .
9. Assumes that $t_{RCD} \leq t_{RCD}(\text{max})$ and $t_{RAD} \leq t_{RAD}(\text{max})$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
10. Assumes that $t_{RCD} \geq t_{RCD}(\text{max})$ and $t_{RAD} \leq t_{RAD}(\text{max})$.
11. Access time is determined by the longer of t_{AA} , t_{CAC} , t_{CPA} .
12. Assumes that $t_{RCD} \leq t_{RCD}(\text{max})$ and $t_{RAD} \geq t_{RAD}(\text{max})$.
13. Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.
14. $t_{OFF}(\text{max})$ and $t_{OEZ}(\text{max})$ define the time at which the output achieves the open circuit condition and is not referenced to output voltage levels. t_{OFF} is determined by the later rising edge of $\overline{\text{RAS}}$ or $\overline{\text{CAS}}$.
15. t_{RASP} defines $\overline{\text{RAS}}$ pulse width in EDO page mode cycles.

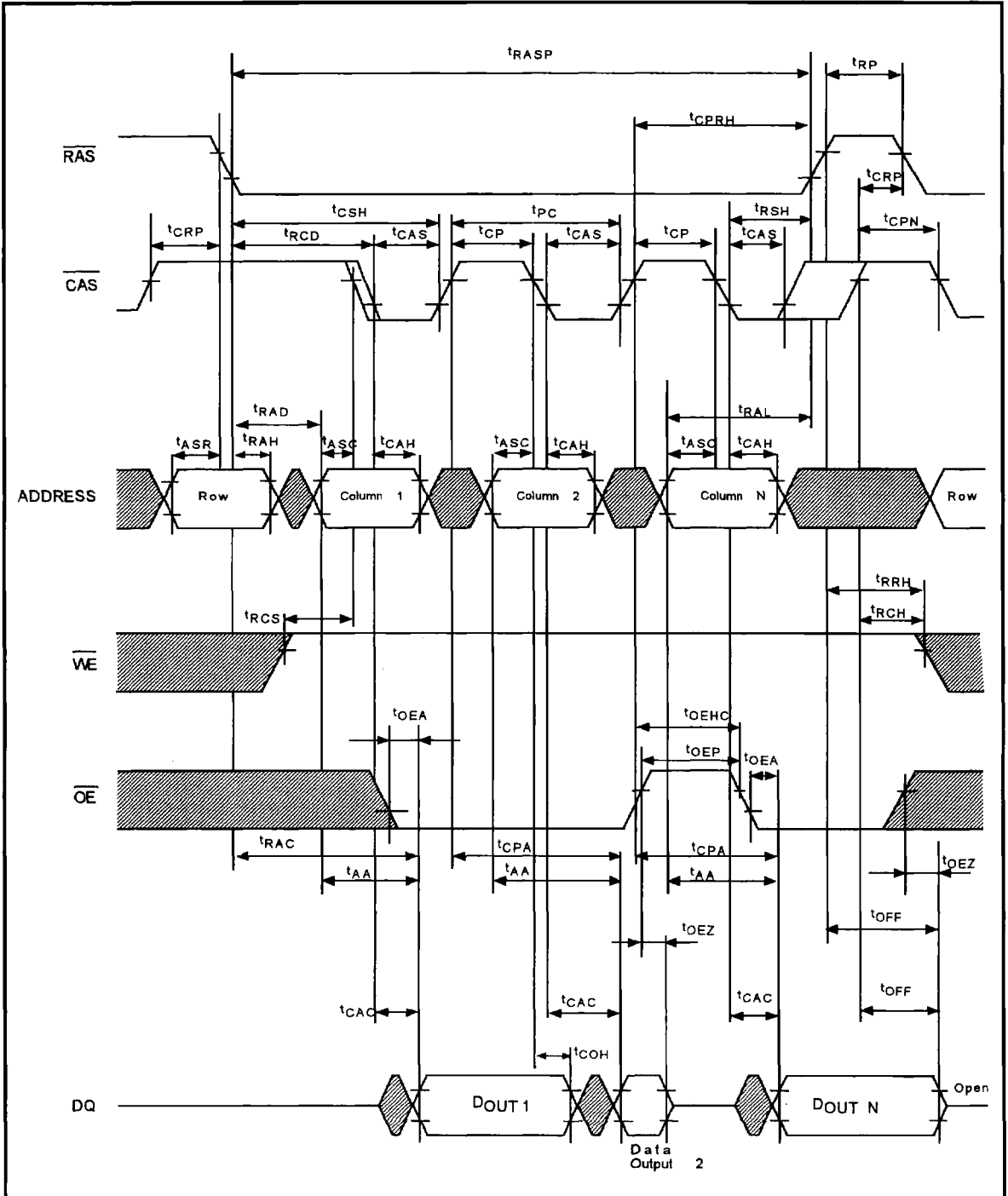
Timing Waveforms
 • Read Cycle



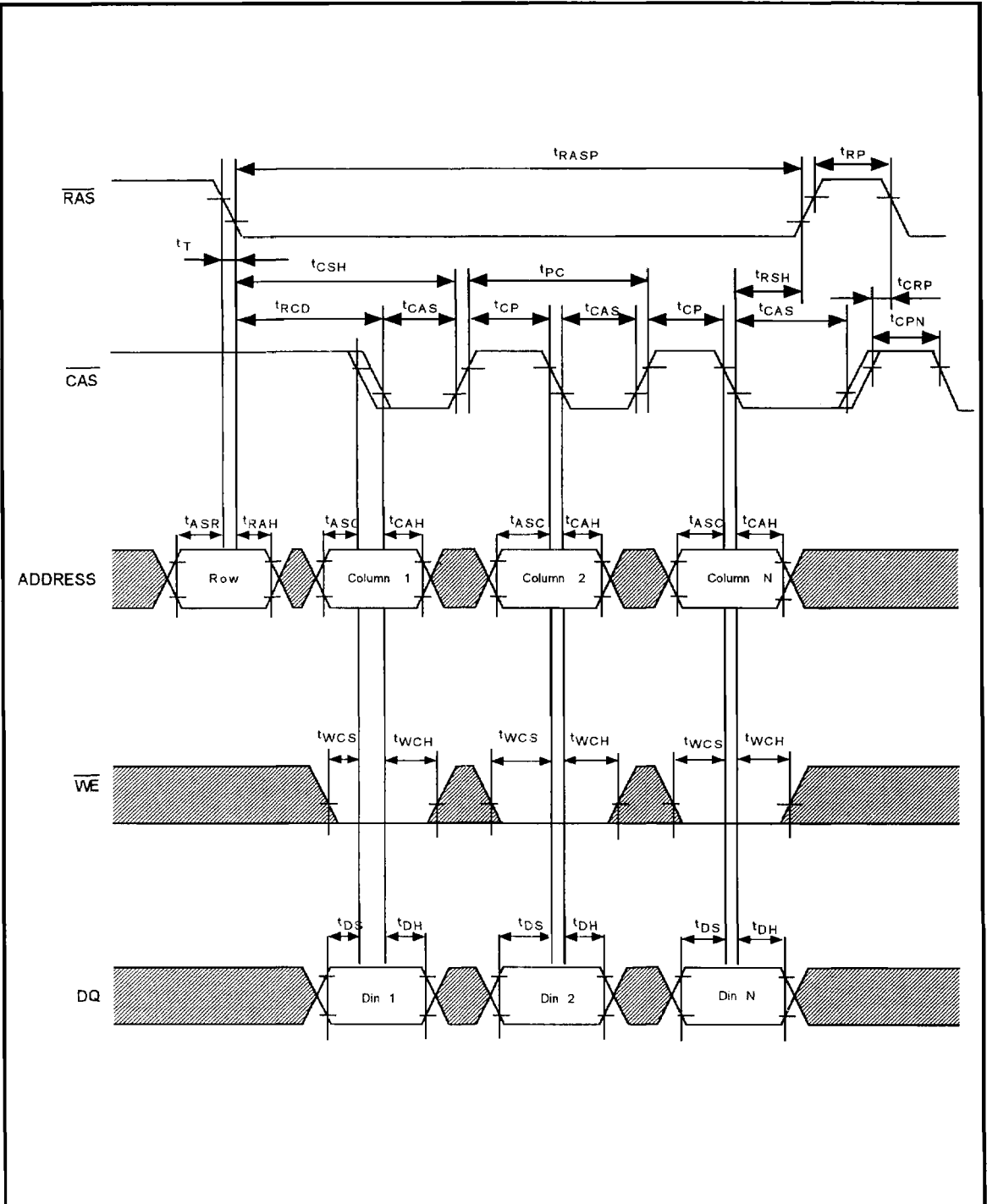
• Early Write Cycle



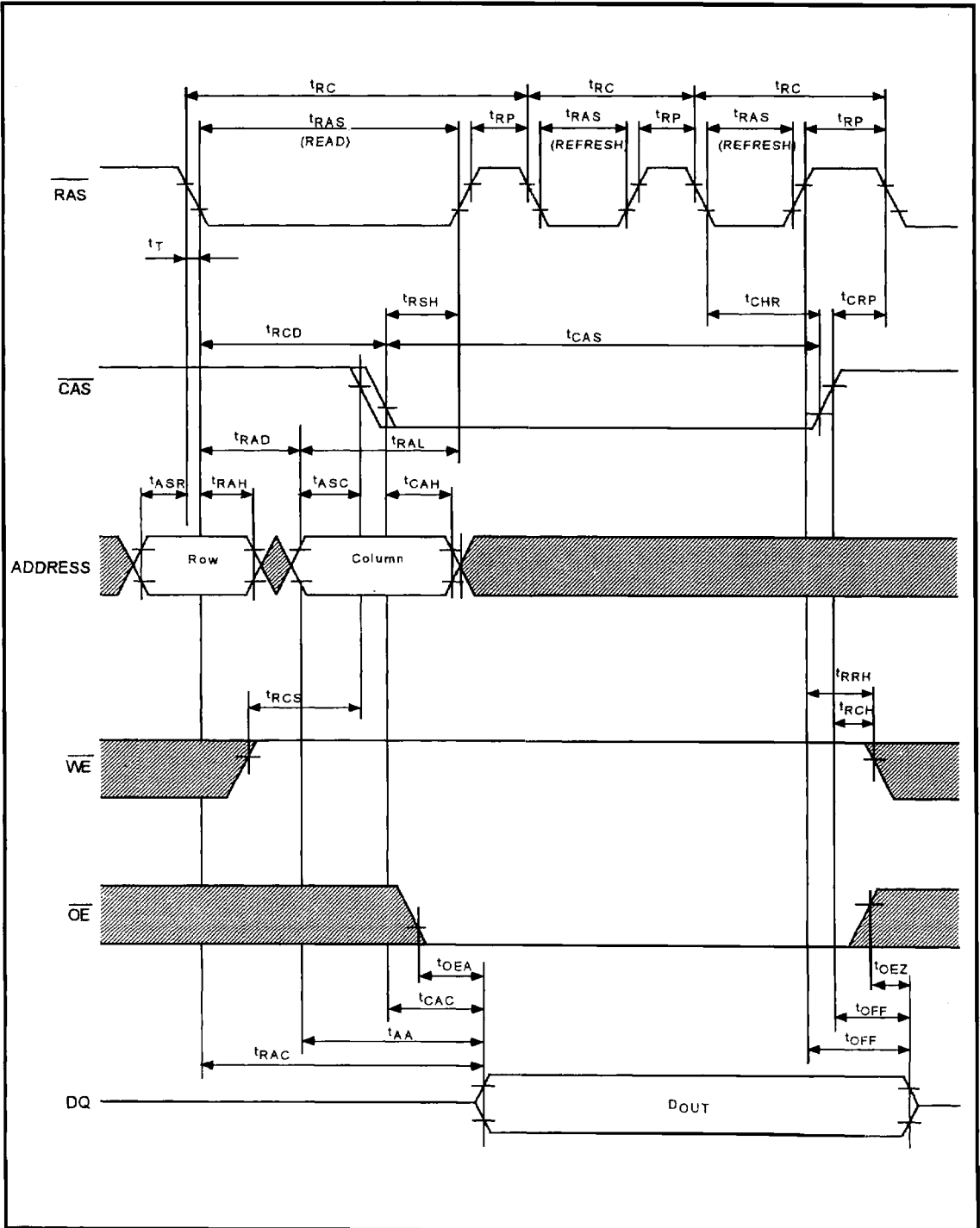
• EDO Page Mode Read Cycle



• EDO Page Mode Early Write Cycle



• Hidden Refresh Cycle



Ordering Information

1 2 3 4 5 6 7 8 9 10
V X X XX XXXXX X X X X X -X

V : VIS Product

1 : RAM Family

M : DRAM SIMM (72pin)

D : DRAM DIMM(168 pin)

6 : Component Package

J : SOJ

T : TSOP

2 : Memory density (word)

1 : 1M

2 : 2M

4 : 4M

8 : 8M

7 : PC board finger plating

G : Gold

S : Tin/lead

3 : I/O width

32 : x32

64 : x64

8 : PC board revision

Blank : none

A : A revision

4 : Operating mode and refresh with different density

17800 : Fast page, 2K ref., 2MX8 DRAM

17805 : EDO, 2K ref. 2MX8 DRAM

18160 : Pass Page, 1K ref. 1MX16 DRAM

18165B : EDO, 1K ref. 1MX16 DRAM

9 : Low Power, Customer specific

Blank : none

L : Low Power

5 : Component revision

Blank : None

A : A revision

B : B revision

10 : Speed

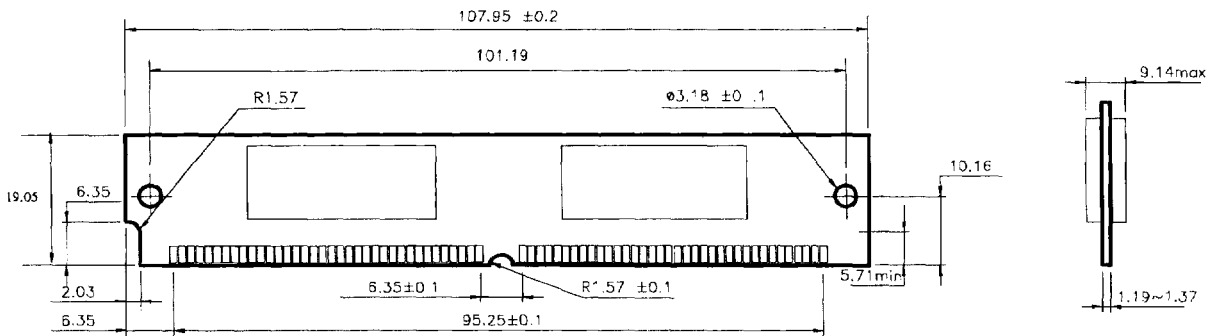
-6 : 60 ns

-7 : 70ns

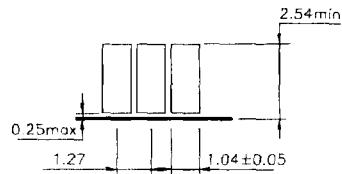
Packaging Information

UNITS: mm

Tolerances: ± 0.13 Unless otherwise specified



Gold & Solder Plating Lead



NOTE: PCB Model No. M116C

The use device is 1Mx16 SOJ DRAM